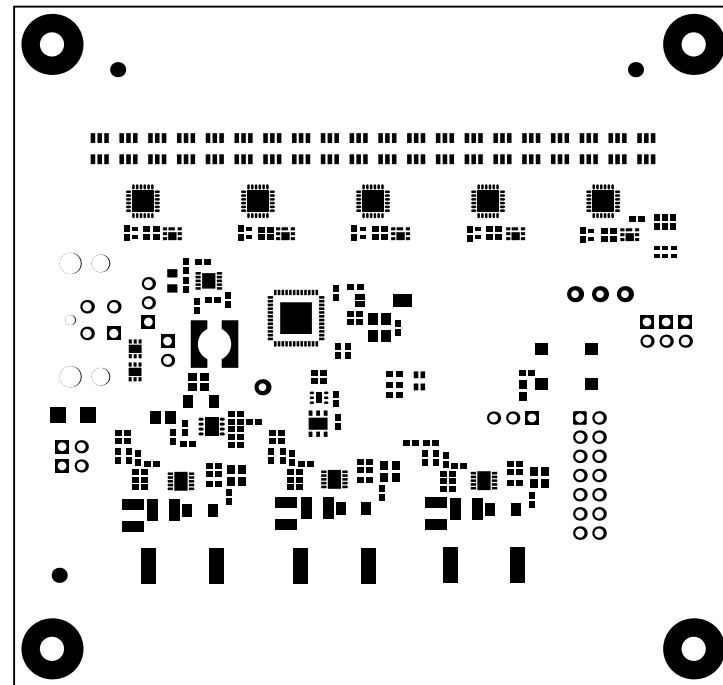
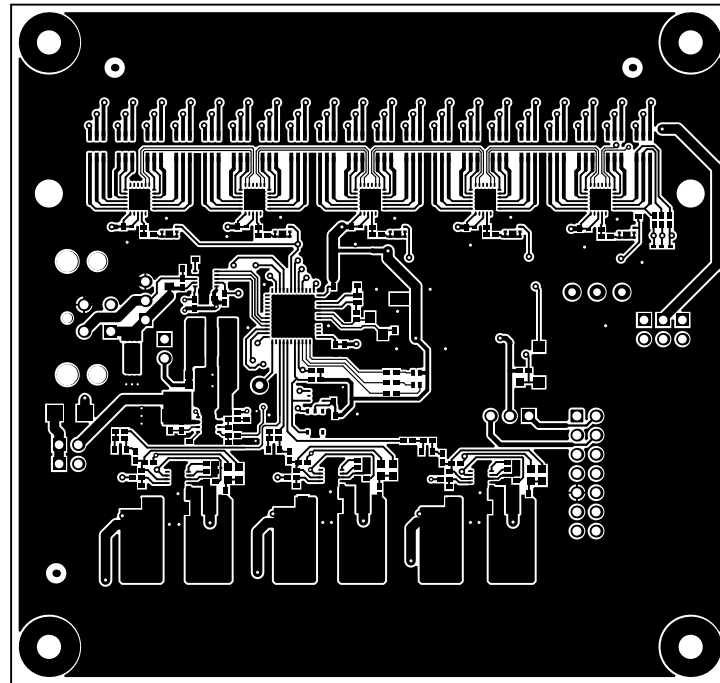


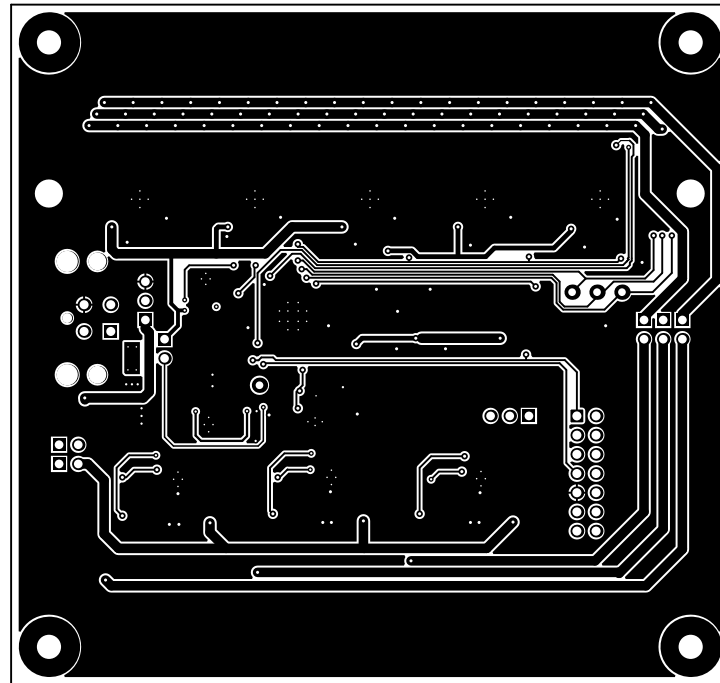
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01437		
PLOT NAME = Top Overlay	GENERATED : 7/5/2017	10:58:05 AM	TEXAS INSTRUMENTS



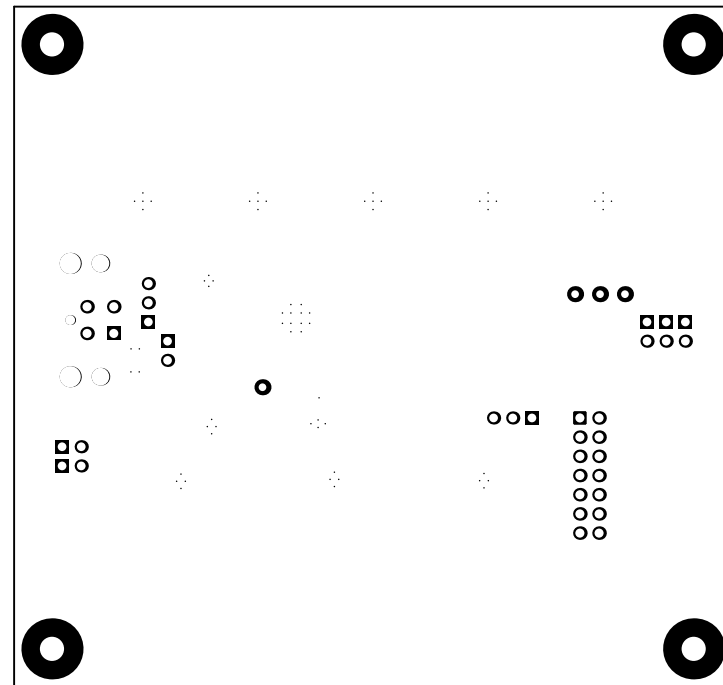
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01437		
PLOT NAME = Top Solder Mask	GENERATED : 7/5/2017 10:58:08 AM	TEXAS INSTRUMENTS	



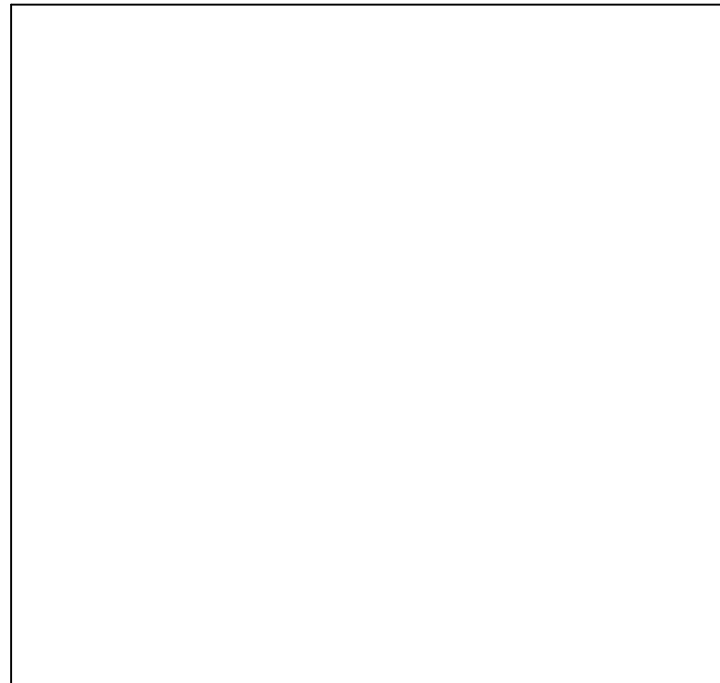
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01437		
PLOT NAME = Top Layer	GENERATED : 7/5/2017	10:58:09 AM	TEXAS INSTRUMENTS



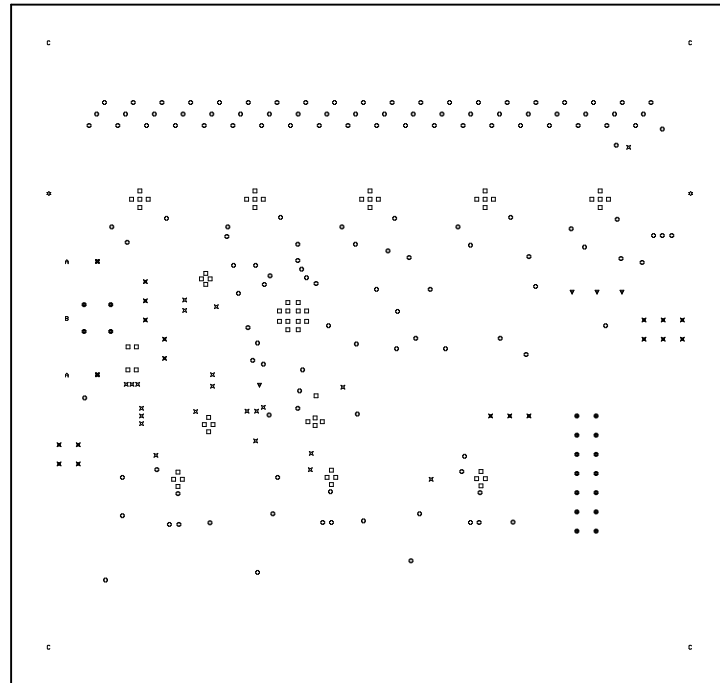
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01437		
PLOT NAME = Bottom Layer	GENERATED : 7/5/2017	10:58:11 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01437		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/5/2017 10:58:13 AM	TEXAS INSTRUMENTS	

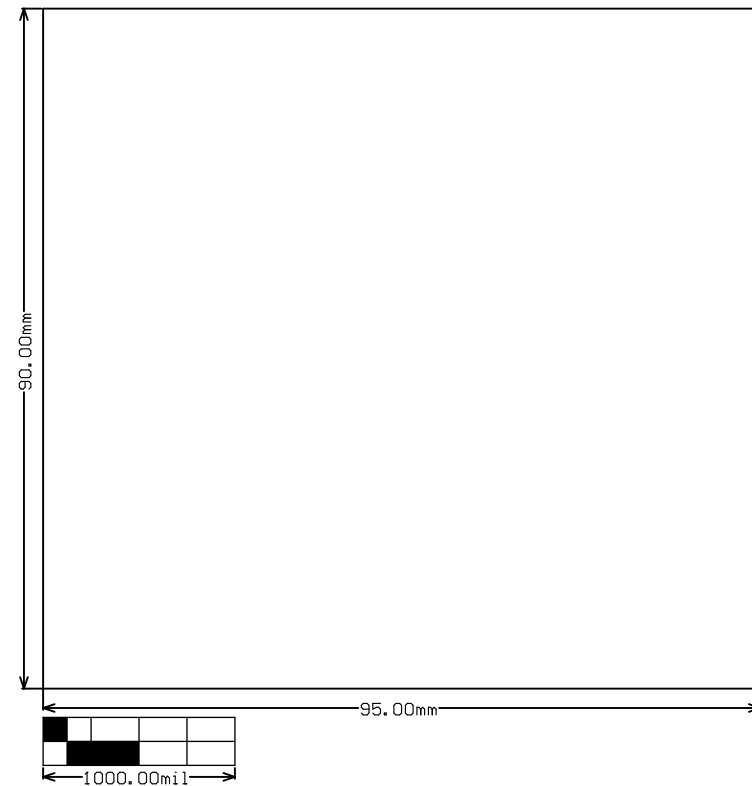


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01437		
PLOT NAME = Bottom Overlay	GENERATED : 7/5/2017 10:58:14 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
B	1	51.18mil (1.300mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	2	92.52mil (2.350mm)	NPTH	Round	Top Layer - Bottom Layer	
⊕	2	110.24mil (2.800mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	2	125.98mil (3.200mm)	NPTH	Round	Top Layer - Bottom Layer	
□	66	7.67mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	22	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	140	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	18	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	18	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
C	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	279 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01437		
PLOT NAME = Drill Drawing	GENERATED : 7/5/2017	10:58:16 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01437	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01437		
PLOT NAME = Board Dimensions	GENERATED : 7/5/2017	10:58:18 AM	TEXAS INSTRUMENTS



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